

#5

<b>Form 1449 (Modified)</b>  <b>Information Disclosure Statement By Applicant</b>  (Use Several Sheets if Necessary)	Atty Docket No.	Application No.:
	NSC1P131X1	10/080,913
	Applicant:	
	Nguyen et al.	
	Filing Date	Group
	2/21/02	2823



### U.S. Patent Documents

Examiner Initial	No.	Patent No.	Date	Patentee	Class	Sub- class	Filing Date
DR	A	6,130,473	10/10/00	Mostafazadeh et al.	257	666	04/02/98
	B						
	C						
	D						
	E						
	F						
	G						
	H						
	I						

### Foreign Patent or Published Foreign Patent Application

Examiner Initial	No.	Document No.	Publication Date	Country or Patent Office	Class	Sub- class	Translation	
							Yes	No
	J							

### Other Documents

Examiner Initial	No.	Author, Title, Date, Place (e.g. Journal) of Publication
DR	O	"Chip Scale Package: Design, Materials, Process, Reliability, and Applications", John H. Lau and S.W. Ricky Lee, Chapter 1, Pages 1-41, (February 28, 1999) McGraw-Hill Professional Publishing; ISBN: 0070383049.
DR	P	"Fundamentals of Microsystem Packaging", Rao R. Tummala, Chapters 2, 10, and 17, (May 8, 2001) McGraw-Hill Professional Publishing; ISBN: 0071371699
	Q	
Examiner <i>DR</i>		Date Considered 3/8/03

Examiner: Initial citation considered. Draw line through citation if not in conformance and not considered. Include copy of this form with next communication to applicant.